Contribution ID: **77** Type: **not specified**

3D-LSI technology for Image Sensors

Thursday, 25 September 2008 09:25 (55 minutes)

Summary

Recently the development of three-dimensional large-scale integration (3D-LSI) has been accelerated and its stage has changed from the research level or limited production level to the investigation level with a view to mass production. The 3D-LSI using Through-Silicon Via (TSV) has simplest structure and it is expected to realize high-performance, high-functionality and high density LSI cube. This presentation covers the current 3D technology for chip size package of image sensor devices and next generation 3D-LSI technologies.

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Session Classification: Invited Talks: 3D Bonding Technology